

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: SAW FILTER
MODEL NO 型号: HDBF07009A24 SMD-24
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: 2006-4-4

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07009A24 used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +70°C
Storage temperature	-40°C to +85°C
RF Power Dissipation	0dBm

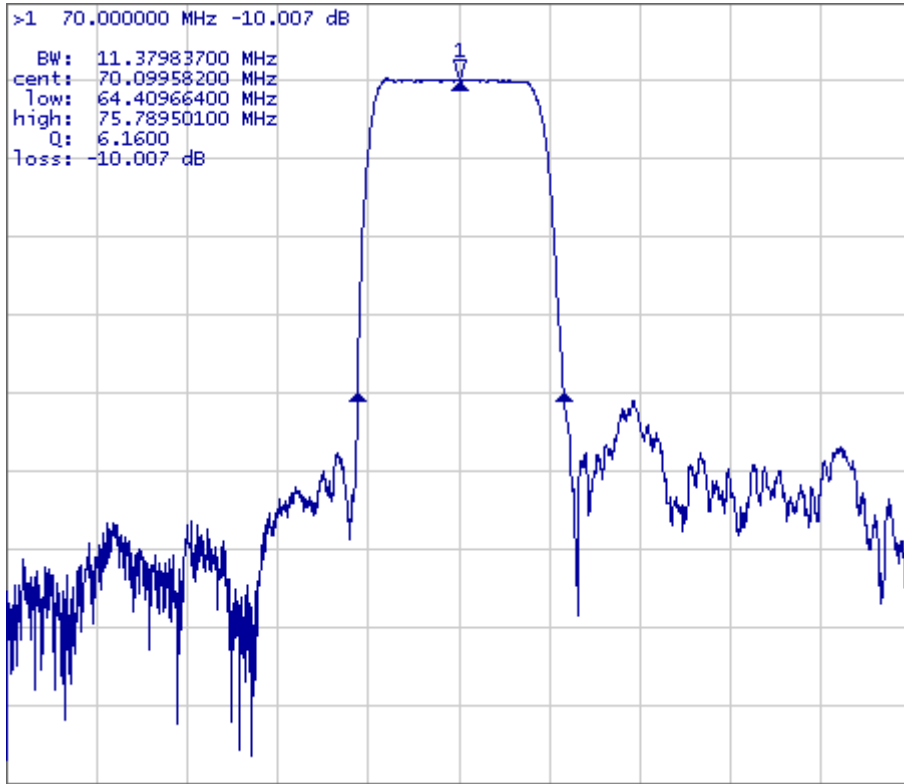
2.2 Electronic Characteristics

Terminating source impedance: 50 ohm and matching network

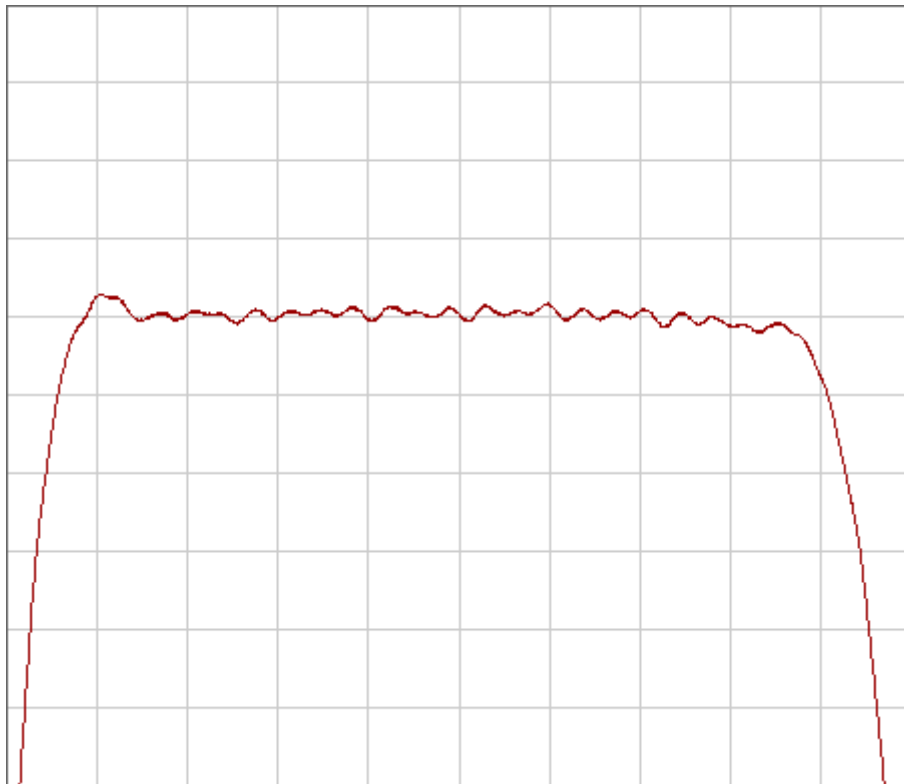
Terminating load impedance: 50 ohm and matching network

		Minimum	Typical	Maximum
Center Frequency	MHz	69.8	70.0	70.2
Insertion Loss	dB	-	10.8	12.0
1dB Bandwidth	MHz	8.2	8.3	-
3dB Bandwidth	MHz	8.9	9.0	-
40dB Bandwidth	MHz	-	11.5	11.8
Amplitude Ripple (Fo +/- 4.0 MHz)	dB	-	0.6	1.0
Group Delay Variation (Fo +/- 4.0 MHz)	nsec	-	70	120
Absolute Delay	usec	-	1.47	-
Ultimate Rejection	dB	40	45	-
Temperature Coefficient of Frequency	ppm/°C	-	-86	-

Frequency Response

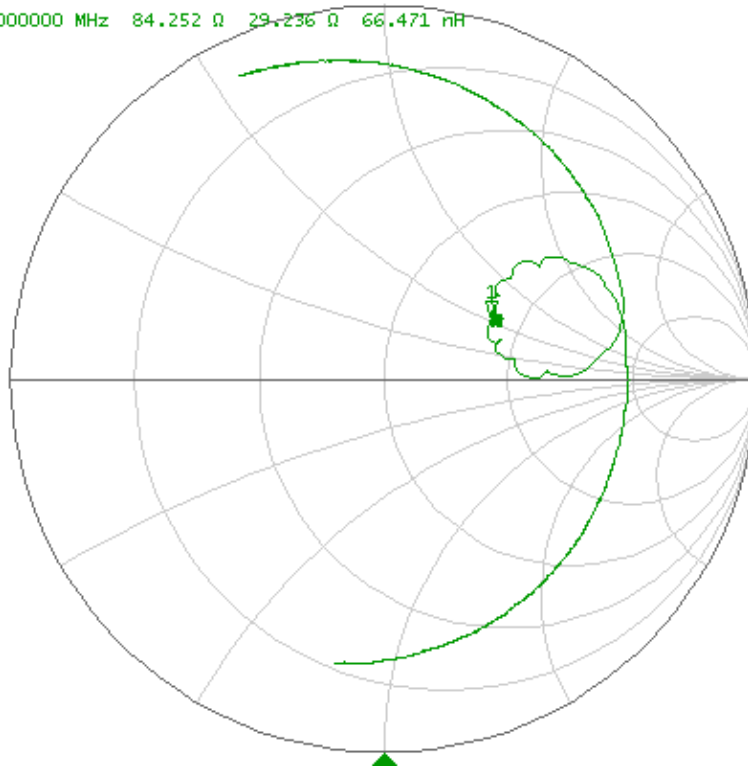


Amplitude Ripple



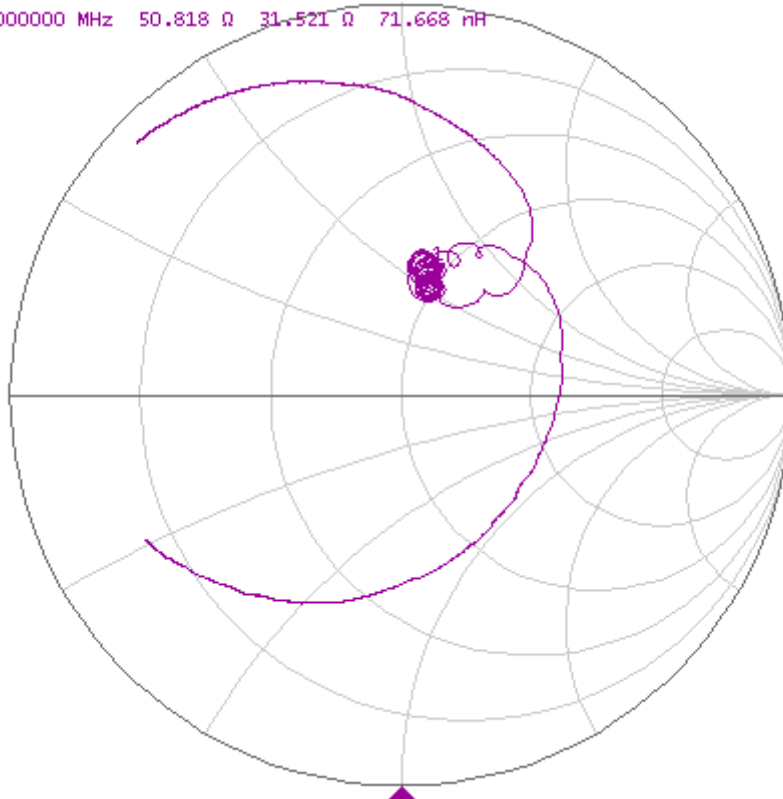
S11 Smith Chart

>1 70.000000 MHz 84.252 Ω 29.236 Ω 66.471 nH



S22 Smith Chart

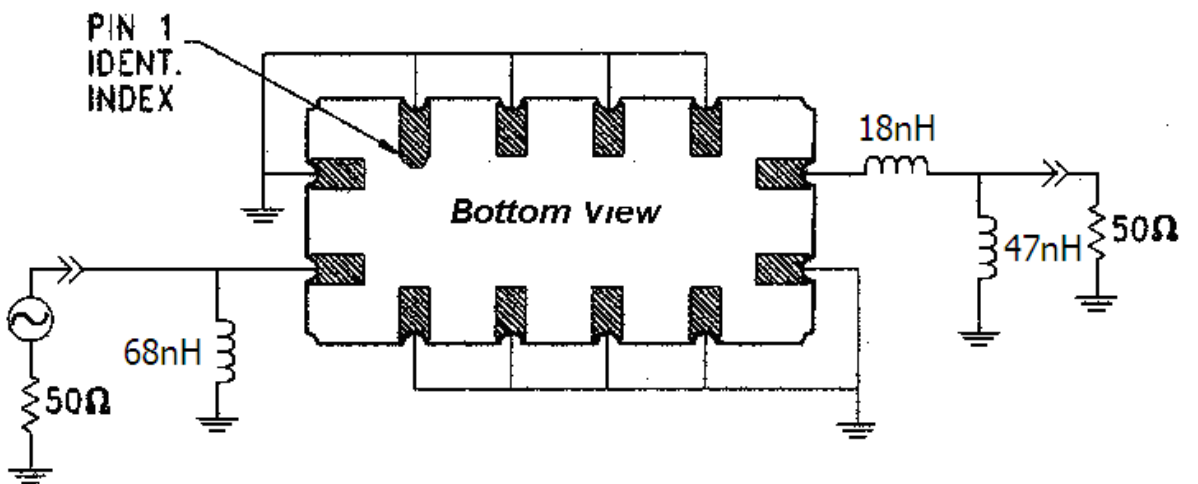
>1 70.000000 MHz 50.818 Ω 31.521 Ω 71.668 nH



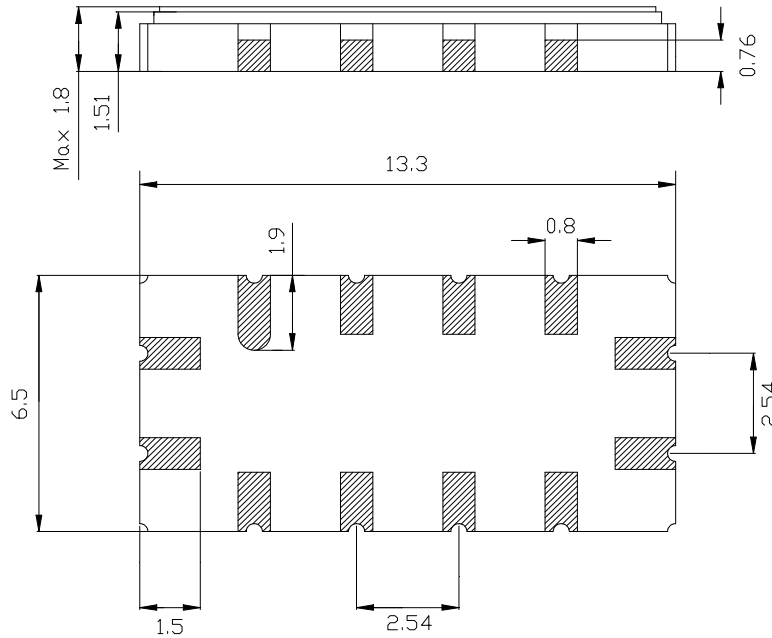
Group Delay



3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. The filter shall fulfill the specifications in 2.2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.